

Separate Sheet

Product Specifications of the RAA604S00

Product No.	RAA604S00
Operating frequency band	863 MHz – 928 MHz
Modulation	2FSK/GFSK: 10/20/40/50/100/150/200/300
/Data rate (kbps)	4FSK/GFSK: 200/400
Current consumption (RF portion)	Vcc = 3.3 V, typ. RX: 6.3 mA, RX wait: 5.8 mA / TX: 20 mA (+10 dBm)
Receiving	-114 dBm(GFSK 10 Kbps、BER<0.1%)
sensitivity	-104 dBm(GFSK 100 Kbps、BER<0.1%)
IEEE802.15.4g/4	Filtering for Dual Sub-GHz Communication
е	Transmit frame automatic generating function *Preamble length: 4 to
-compliant H/W	1000 bytes setting possible
function	Automatic ACK reply/receiving function support
Package	32-pin 5 mm x 5 mm QFN

RL78/G1H main specifications

Item		R5F11FLJ	R5F11FLK	R5F11FLL
Code flash memory (KB)		256 KB	384 KB	512 KB
Data flash memory (KB)		8 KB	8 KB	8 KB
RAM (KB)		24 KB	32 KB	48 KB
Address space		1 MB		
Main system clock	High-speed system clock	X1 (crystal/ceramic) oscillator, external main system clock input (EXCLK) HS (high-speed main) mode: 1 to 20 MHz (VDD = 2.7 to 3.6 V) HS (high-speed main) mode: 1 to 16 MHz (VDD = 2.4 to 3.6 V) LS (low-speed main) mode: 1 to 8 MHz (VDD = 1.8 to 3.6 V)		
	High-speed on- chip	HS (high-speed main) mode: 1 to 32 MHz (VDD = 2.7 to 3.6 V), HS (high-speed main) mode: 1 to 16 MHz (VDD = 2.4 to 3.6		

	oscillator clock	V),	
	(fIH)	LS (low-speed main) mode: 1 to 8 MHz (VDD = 1.8 to 3.6	
		V),	
		XT1 (crystal) oscillator, external subsystem clock input	
Subsystem	clock	(EXCLKS)	
		32.768 kHz (TYP.)	
Low-speed on-chip oscillator clock		15 kHz (TYP.)	
RF base clo	ock	48 MHz (TYP.)	
RF slow clock		External clock input for RF unit (EXCLKS) 32.768 kHz (TYP.)	
General-pu	rpose register	8 bit x 32 registers (8 bit x 8 registers x 4 banks)	
		0.03125 us (High-speed on-chip oscillator clock: fIH = 32	
Minimum ir	struction	MHz operation)	
execution t	ime	0.05 us (High-speed system clock: fMX = 20 MHz operation)	
		30.5 us (Subsystem clock: fSUB = 32.768 kHz operation)	
		-instruction set (8/16 bit)	
		Adder and subtractor/ logical operation (8/16 bit)	
		• Multiplication (8 bit x 8 bit, 16 bit x 16 bit), Division (16 bit	
Instruction	set	÷ 16 bit, 3 bit ÷ 32 bit)	
		 Multiplication and Accumulation (16 bit x 16 bit + 32 bit) 	
		\cdot Rotate, barrel shift, and bit manipulation (set, reset, test,	
	1	and boolean operation), etc.	
	Total	41	
I/O port	CMOS I/O	26	
	CMOS input	5	
	CMOS output	1	
	N-ch open-drain		
	I/O	4	
	(6 V tolerance)		
	GPIO (RF unit)	5	
SubGHz Operating		863 MHz - 928 MHz	
RF	frequency band		

transceive r	Modulation /Data rate (kbps)	2FSK/ GFSK : 10/ 20/ 40/ 50/ 100/ 150/ 200/ 300 4FSK/ GFSK : 200/ 400
	Current consumption (RF portion)	Vcc = 3.3 V, typ. RX:6.3 mA, RX wait: 5.8 mA / TX: 20 mA (+10 dBm)
	Receiving	-114 bdBm(GFSK 10 bKbps、BER <0.1%)
	sensitivity	-104 bdBm(GFSK 100 bKbps、BER <0.1%)
	IEEE802.15.4g/	Filtering for Dual Sub-GHz Communication
	4e	Transmit frame automatic generating function *Preamble
	-compliant H/W	length: 4 to 1000 byte setting possible
	function	Automatic ACK reply/ receiving function support
	16-bit timer	9 channels
	Watchdog timer	1 channel
Timer	Real-time clock (RTC)	1 channel
	12-bit interval timer	1 channel
	Timer Output	1 channel
		2
		· 2.44 kHz, 4.88 kHz, 9.76 kHz, 1.25 MHz, 2.5 MHz, 5 MHz, 10 MHz
Clock outpu	ut/buzzer output	(Main system clock: fMAIN = 20 MHz operation)
		= 20 MHz operation).024 kHz, 2.048 kHz, 4.096 kHz, 8.192
		kHz, 16.384 kHz, 32.768 kHz
		(Subsystem clock: fSUB = 32.768 kHz operation)
10-bit resolution		6 channels
A/D converter		
Serial interface		CSI/UART: 2 channels OSI: 1 channel
	I2C bus	2 channels

Multiplier and divider/multiply- accumulator Data transfer controller		Multiplication: 16 bit x 16 bit = 32 bit (Unsigned or signed) Division: 32 bit x 32 bit = 32 bit (Unsigned) Multiply-accumulate: 16 bit x 16 bit + 32 bit = 32 bit (Unsigned or signed)	
(DTC)		21 sources	
Vectored	Internal	26	
interrupt sources	External	7	
		Reset by RESET pin	
		Internal reset by watchdog timer	
		 Internal reset by power-on-reset 	
Reset		 Internal reset by voltage detector 	
		Internal reset by illegal instruction execution (Note 3)	
		 Internal reset by RAM parity error 	
		Internal reset by illegal-memory access	
Power-on-r	eset circuit	·ower-on-reset circuit 1.51 (TYP.)	
		(TYP.)r-down-reset: 1.50 (TYP.)	
Voltage det	ector	·voltage detector: 1.88 V to 3.13 V (10 stages)	
Voltage detector		voltage detector: 1.84 V to 3.05 V (10 stages)	
On-chip debug function		Provided	
Power supply voltage		VDD = 1.8 - 3.6 V	
Operating ambient		TA = -40 °C - +85 °C (A: Consumer applications, D:	
temperature		Industrial applications)	
Package		64-pin 9 mm x 9 mm VQFN (0.5 mm pitch)	